



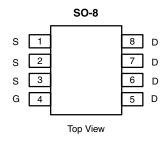
# N-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY				
V <sub>DS</sub> (V)	$r_{DS(on)}\left(\Omega\right)$	I <sub>D</sub> (A)		
30	0.0045 at V <sub>GS</sub> = 10 V	22		
	0.005 at V <sub>GS</sub> = 4.5 V	19		
	0.0075 at V <sub>GS</sub> = 2.5 V	17		

#### **FEATURES**

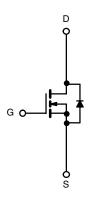
- TrenchFET<sup>®</sup> Power MOSFETs: 2.5 V Rated
- 100 % R<sub>G</sub> Tested





Ordering Information: Si4442DY-T1

Si4442DY-T1-E3 (Lead (Pb)-free)



N-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATINGS</b> $T_A = 25$ °C, unless otherwise noted					
Parameter		Symbol	10 sec	Steady State	Unit
Drain-Source Voltage		V <sub>DS</sub>	30		V
Gate-Source Voltage		V <sub>GS</sub>	± 12		
Continuous Drain Current /T 150 °C\2	T <sub>A</sub> = 25 °C	- I <sub>D</sub>	22	15	
Continuous Drain Current (T <sub>J</sub> = 150 °C) <sup>a</sup>	T <sub>A</sub> = 70 °C		17	11	
Pulsed Drain Current (10 µs Pulse Width)		I <sub>DM</sub>	60		A
Continuous Source Current (Diode Conduction) <sup>a</sup>		I <sub>S</sub>	2.9	1.3	
	T <sub>A</sub> = 25 °C	P <sub>D</sub>	3.5	1.6	W
Maximum Power Dissipation <sup>a</sup>	T <sub>A</sub> = 70 °C		2.2	1	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150		°C

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Marian and Luncking to Ambigueta	t ≤ 10 sec	- R <sub>thJA</sub>	29	35	°C/W	
Maximum Junction-to-Ambient <sup>a</sup>	Steady State		67	80		
Maximum Junction-to-Foot (Drain)	Steady State	R <sub>thJF</sub>	13	16		

#### Notes:

a. Surface Mounted on 1" x 1" FR4 Board.

<sup>\*</sup> Pb containing terminations are not RoHS compliant, exemptions may apply.

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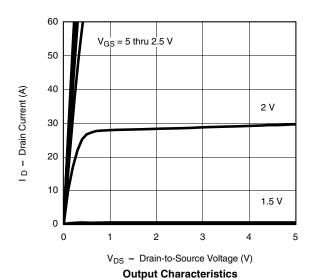
Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit	
Static			•	<u>'</u>	l l		
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$ 0.6 1.5		1.5	V		
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$	V <sub>DS</sub> = 0 V, V <sub>GS</sub> = ± 12 V		± 100	nA	
Zero Gate Voltage Drain Current		V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V			1		
	IDSS	V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C			5	μΑ	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	30			Α	
		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 22 A		0.0035 0.0045			
Drain-Source On-State Resistance <sup>a</sup>	r <sub>DS(on)</sub>	$V_{GS} = 4.5 \text{ V}, I_D = 19 \text{ A}$		0.0041	0.005	Ω	
		$V_{GS} = 2.5 \text{ V}, I_D = 17 \text{ A}$		0.0062	0.0075		
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 22 A		100		S	
Diode Forward Voltage <sup>a</sup>	$V_{SD}$	I <sub>S</sub> = 2.9 A, V <sub>GS</sub> = 0 V		0.75	1.1	V	
Dynamic <sup>b</sup>							
Total Gate Charge	Qg			36	50		
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 22 \text{ A}$		8		nC	
Gate-Drain Charge	$Q_{gd}$			10.5			
Gate Resistance	$R_{g}$		0.5	1.5	2.6	Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			17	30		
Rise Time	t <sub>r</sub>	$t_r$ $V_{DD} = 15 \text{ V}, R_L = 15 \Omega$		11	20		
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D\cong$ 1 A, $V_{GEN}$ = 10 V, $R_g$ = 6 $\Omega$		125	180	ns	
Fall Time	t <sub>f</sub>			47	70		
Source-Drain Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 2.9 A, di/dt = 100 A/μs		50	80		

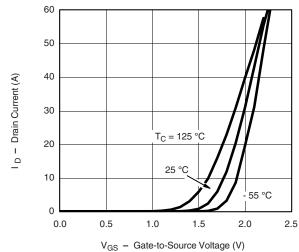
#### Notes:

- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





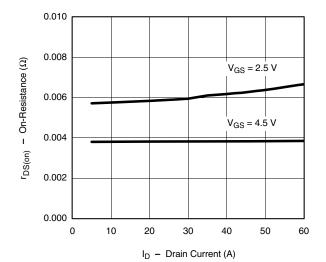
**Transfer Characteristics** 



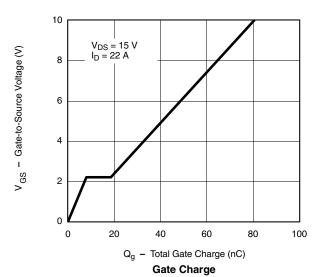


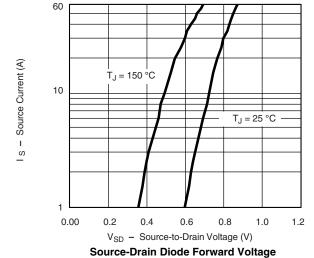


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On-Resistance vs. Drain Current

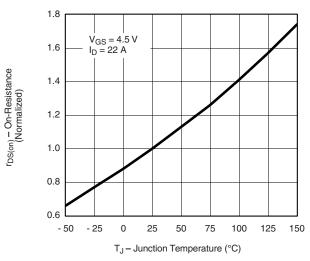




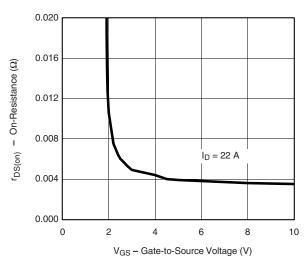
6000 5000 Ciss 4000 3000 1000 Coss 1000 0 6 12 18 24 30

V<sub>DS</sub> - Drain-to-Source Voltage (V)





On-Resistance vs. Junction Temperature

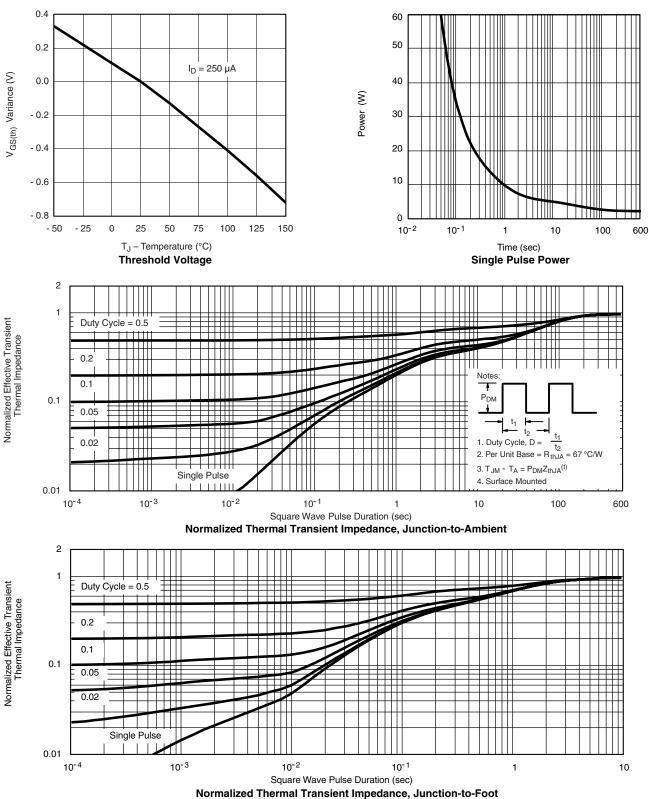


On-Resistance vs. Gate-to-Source Voltage

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## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



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